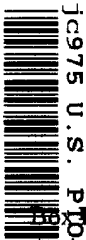


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Docket No. 005794 ALRT/ETCH/CONE/

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent Application  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Re: Inventor(s): Mark N. Kawaguchi, Huong T. Nguyen, Nikolaos Bekiaris, James S. Papanu  
Title: A METHOD OF PHOTORESIST REMOVAL IN THE PRESENCE OF A DIELECTRIC LAYER  
HAVING A LOW K-VALUE



Transmitted herewith is the patent application identified above, including:

- ☒ Specification, claims and abstract, totaling 35 pages.
- ☒ Drawings totaling 6 pages, ☐ Formal ☒ Informal.
- ☒ Executed Declaration and Power of Attorney.
- ☒ Assignment of the invention to Applied Materials, Inc.
- ☒ Assignment Recordation Cover Sheet

FEE CALCULATION					
Fee Items	Claims Filed	Included With Basic Fee	Extra Claims	Fee Rate	Total
Total Claims	25	- 20 =	5	X \$18.00	\$ 90.00
Independent Claims	2	- 3 =	0	X \$80.00	0.00
Basic Filing Fee				\$740.00	\$740.00
TOTAL FEES					\$830.00

- ☒ The Commissioner is hereby authorized to charge \$830.00 to Deposit Account No. 50-1074.
- ☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 50-1074. A duplicate copy of this transmittal is enclosed.
- ☒ Please address all future correspondence to:

PATENT COUNSEL  
APPLIED MATERIALS, INC.  
Legal Affairs Department  
P.O. Box 450A  
Santa Clara, CA 95052

I hereby certify that this correspondence is being deposited with the United States Postal Service as express mail in an envelope addressed to: Box Patent Application, Assistant Commissioner for Patents, Washington, D.C. 20231

Express Mail Receipt No. EL 672745889 US

Date of Deposit 10-15-01

Signature

Respectfully submitted,

Robert W. Mulcahy  
Registration No. 25,436